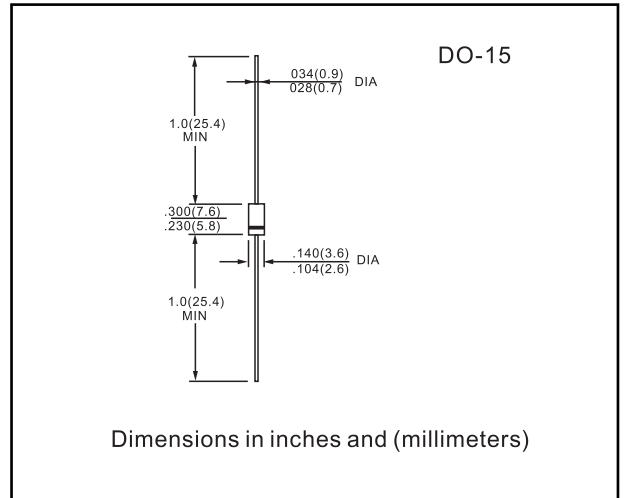




**FEATURES**

- High efficiency
- Low power losses
- Very low switching losses
- Low reverse current
- High surge capability



**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

**ABSOLUTE RATINGS** (limiting values)

Symbol	Parameter	Value	Unit
$I_{FRM}$	Repetive Peak Forward Current	$t_p \leq 20\mu s$	A
$I_F (AV)$	Average Forward Current *	$T_a = 75^\circ C$ $\delta = 0.5$	A
$I_{FSM}$	Surge non Repetitive Forward Current	$t_p = 10ms$ Sinusoidal	A
$P_{tot}$	Power Dissipation *	$T_a = 55^\circ C$	W
$T_{stg}$ $T_j$	Storage and Junction Temperature Range	- 55 to + 150 - 55 to + 150	$^\circ C$
$T_L$	Maximum Lead Temperature for Soldering during 10s at 4mm from Case	230	$^\circ C$

Symbol	Parameter	BYT 11-			Unit
		600	800	1000	
$V_{RRM}$	Repetitive Peak Reverse Voltage	600	800	1000	V

**ELECTRICAL CHARACTERISTICS**

STATIC CHARACTERISTICS

Symbol	Test Conditions	Min.	Typ.	Max.	Unit
$I_R$	$T_j = 25^\circ C$ $V_R = V_{RRM}$			20	$\mu A$
$V_F$	$T_j = 25^\circ C$ $I_F = 1A$			1.3	V

RECOVERY CHARACTERISTICS

Symbol	Test Conditions	Min.	Typ.	Max.	Unit
$t_{rr}$	$T_j = 25^\circ C$ $I_F = 0.5A$ $I_R = 1A$ $I_{rr} = 0.25A$			100	ns



RATINGS AND CHARACTERISTIC CURVES

BYT11-600 THRU BYT11-1000

Figure 1. Maximum average power dissipation versus average forward current.

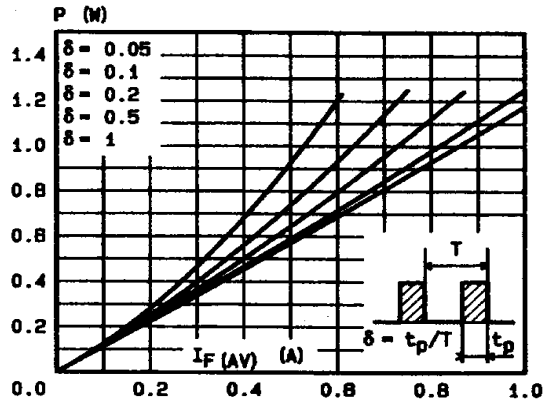


Figure 2. Average forward current versus ambient temperature.

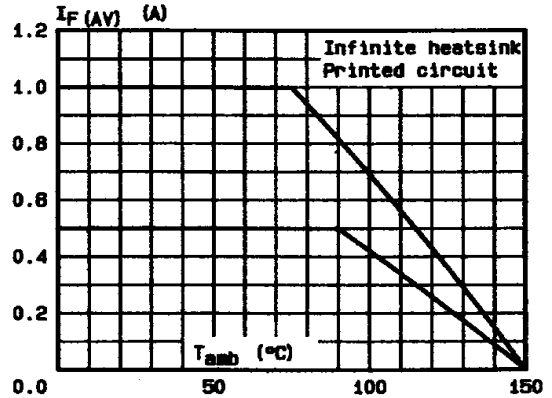


Figure 3. Thermal resistance versus lead length.

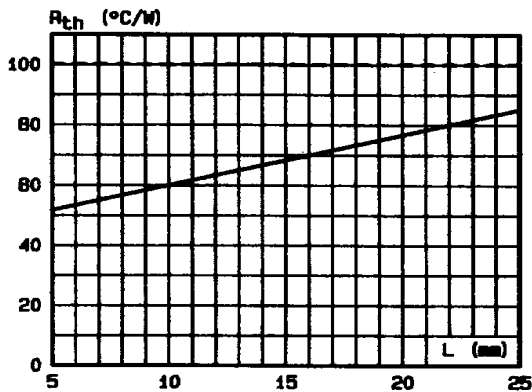


Figure 4. Transient thermal impedance junction-ambient for mounting n<sup>2</sup> versus pulse duration (L = 10 mm).

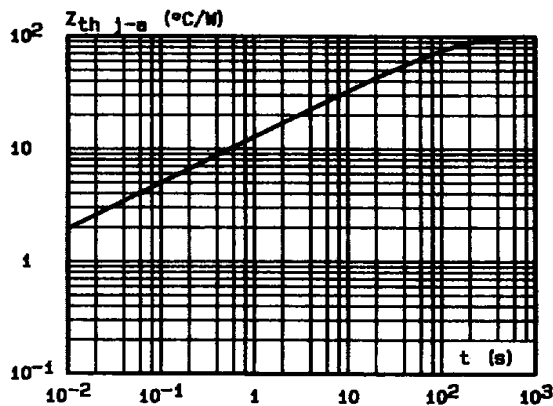


Figure 5. Peak forward current versus peak forward voltage drop (maximum values).

